

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

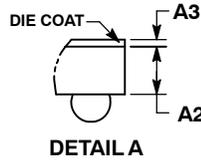
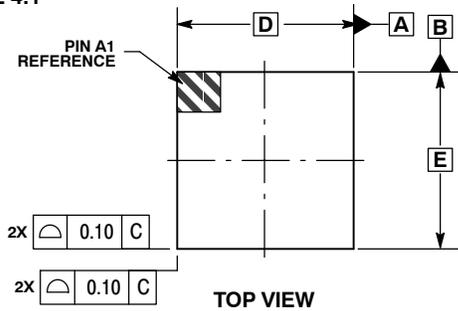


WLCSP25, 2.06x2.06  
CASE 567FZ  
ISSUE O

DATE 17 JUL 2012



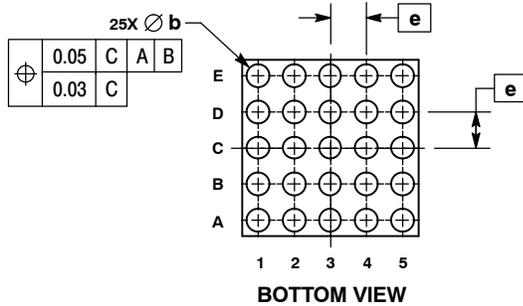
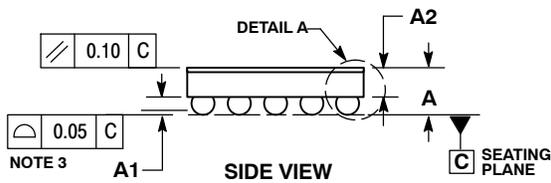
SCALE 4:1



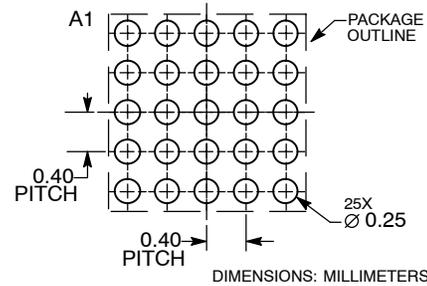
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.36 REF	
A3	0.04 REF	
b	0.24	0.29
D	2.06 BSC	
E	2.06 BSC	
e	0.40 BSC	



### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP25, 2.06X2.06	PAGE 1 OF 2

